

**Amendments to the Specification:**

Please replace the paragraph beginning on page 8, line 1 with the following paragraph:

In addition, although only partially densified substrates are discussed above, a combination of fully and partially densified substrates, such as a solid/powder substrate may be utilized where appropriate. In such an exemplary embodiment, as shown in ~~Figures 3a to 3b~~ Figures 3a to 3c, any combination of fully densified, partially densified and porous substrate materials can be used in forming the cutting elements of the present invention, allowing for the control, and thus, tailoring of the sintering induced stresses on the ultra hard material layer and on the interface between the ultra hard material layer and the substrate. For example, in Figure 3a a two component substrate 10 is utilized wherein the outer portion 18 of the substrate is not fully densified forming a not-fully densified region 20 surrounding a more fully or a fully densified region 11. Alternatively, as shown in Figures 3b and 3c, the two component substrate 10 might be fully densified except for an interfacial portion 22 of the substrate in direct contact with the ultra-hard layer 14 of the cutting element, and which in the exemplary embodiment shown in Figure 3b is surrounded by the ultra hard material. In this regard a non-fully densified region 20 extends over the fully densified region 11 and the ultra hard material layer encapsulates the non-fully densified region extending to the fully densified region 11, as for example shown in Figure 3b. In an alternate exemplary embodiment, the non-fully densified region 20 may take on any suitable configuration, such as rectangular or stepped, such that a suitable interface, uniform or non-uniform, 22 between the substrate 10 and ultra-hard layer 14 is formed, as for example shown in Figure 3c. The ultra hard material layer may be in contact with both the fully densified region and the partially densified region as for example shown in Figures 3a to 3c.